

# HM6287 Series

Maintenance Only

65536-word x 1-bit High Speed CMOS Static RAM

Refer to HM6287H Series

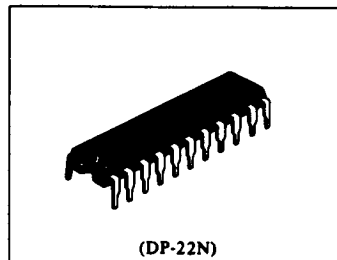
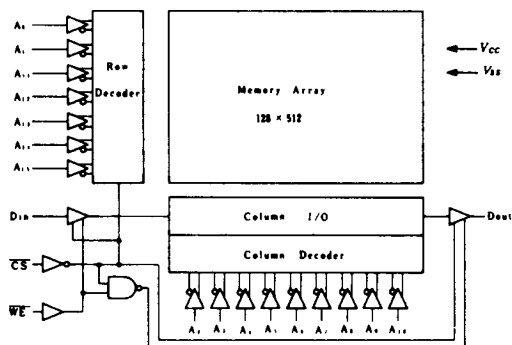
## FEATURES

- High Speed: Fast Access Time 45/55/70ns (max.)
- Single 5V Supply and High Density 22 Pin Package
- Low Power Standby and Low Power Operation  
Standby: 100 $\mu$ W (typ.)/10 $\mu$ W (typ.) (L-version)  
Operation: 300mW (typ.)
- Completely Static Memory  
No Clock or Timing Strobe Required
- Equal Access and Cycle Times
- Directly TTL Compatible: All Inputs and Output
- Capability of Battery Back Up Operation (L-version)

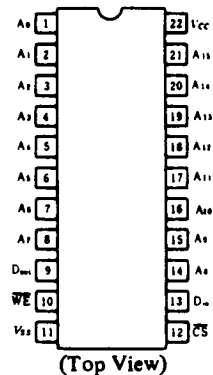
## ORDERING INFORMATION

Type No.	Access Time	Package
HM6287P-45	45ns	300 mil 22 pin Plastic DIP
HM6287P-55	55ns	
HM6287P-70	70ns	
HM6287LP-45	45ns	
HM6287LP-55	55ns	
HM6287LP-70	70ns	

## BLOCK DIAGRAM



## PIN ARRANGEMENT



## ■ TRUTH TABLE

$\overline{CS}$	$\overline{WE}$	Mode	$V_{CC}$ Current	Dout Pin	Ref. Cycle
H	X	Not Selected	$I_{SB}, I_{SB1}$	High Z	—
L	H	Read	$I_{CC}$	Dout	Read Cycle
L	L	Write	$I_{CC}$	High Z	Write Cycle

## ■ ABSOLUTE MAXIMUM RATINGS

Item	Symbol	Rating	Unit
Voltage on Any Pin Relative to $V_{SS}$	$V_T$	$-0.5^{*1}$ to +7.0	V
Power Dissipation	$P_T$	1.0	W
Operating Temperature	$T_{opr}$	0 to +70	°C
Storage Temperature	$T_{stg}$	-55 to +125	°C
Temperature Under Bias	$T_{bias}$	-10 to +85	°C

Note) \*1. -3.5V for pulse width  $\leq 20$ ns

■ RECOMMENDED DC OPERATING CONDITIONS ( $T_a = 0$  to +70°C)

Item	Symbol	min	typ	max	Unit
Supply Voltage	$V_{CC}$	4.5	5.0	5.5	V
	$V_{SS}$	0	0	0	V
Input Voltage	$V_{IH}$	2.2	—	6.0	V
	$V_{IL}$	$-0.5^{*1}$	—	0.8	V

Note) \*1. -3.0V for pulse width  $\leq 20$ ns

■ DC AND OPERATING CHARACTERISTICS ( $V_{CC} = 5V \pm 10\%$ ,  $V_{SS} = 0V$ ,  $T_a = 0$  to +70°C)

Item	Symbol	Test Conditions	min	typ <sup>*1</sup>	max	Unit
Input Leakage Current	$ I_{LI} $	$V_{CC} = 5.5V$ , $V_{in} = V_{SS}$ to $V_{CC}$	—	—	2.0	$\mu A$
Output Leakage Current	$ I_{LO} $	$\overline{CS} = V_{IH}$ , $V_{out} = V_{SS}$ to $V_{CC}$	—	—	2.0	$\mu A$
Operating Power Supply Current	$I_{CC}$	$\overline{CS} = V_{IL}$ , $I_{out} = 0mA$ , min. cycle	—	60	100	mA
Standby Power Supply Current	$I_{SB}$	$\overline{CS} = V_{IH}$ , min. cycle	—	10	30	mA
	$I_{SB1}$	$\overline{CS} \geq V_{CC} - 0.2V$ , $0V \leq V_{in} \leq 0.2V$ or $V_{CC} - 0.2V \leq V_{in}$	—	0.02	2.0	mA
Output Voltage	$I_{OL}$	$I_{OL} = 8mA$	—	—	0.4	V
	$I_{OH}$	$I_{OH} = -4.0mA$	2.4	—	—	V

Notes) \*1. Typical limits are at  $V_{CC} = 5.0V$ ,  $T_a = 25^\circ C$  and specified loading.

\*2. This characteristics is guaranteed only for L-version.

■ CAPACITANCE ( $f = 1MHz$ ,  $T_a = 25^\circ C$ )

Item	Symbol	Test Conditions	min	typ	max	Unit
Input Capacitance	$C_{in}$	$V_{in} = 0V$	—	—	5	pF
Output Capacitance	$C_{out}$	$V_{out} = 0V$	—	—	7.5	pF

Note) This parameter is sampled and not 100% tested.

# ■ AC CHARACTERISTICS ( $V_{CC} = 5V \pm 10\%$ , $T_a = 0$ to $+70^\circ\text{C}$ , unless otherwise noted)

## ● AC TEST CONDITIONS

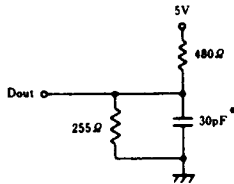
Input Pulse Levels:  $V_{SS}$  to 3.0V

Input Rise and Fall Times: 5ns

Input and Output Timing Reference Levels: 1.5V

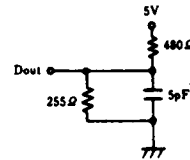
Output Load: See Figure

### Output Load A



\*Including scope & jig capacitance

### Output Load B

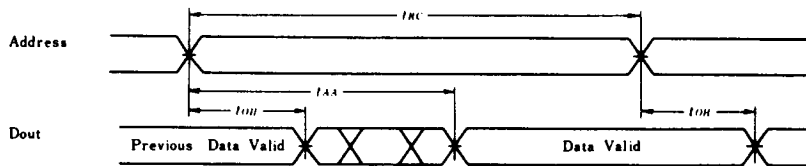


\*Including scope & jig capacitance

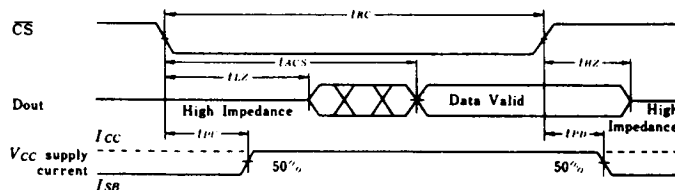
## ● READ CYCLE

Item	Symbol	HM6287-45		HM6287-55		HM6287-70		Unit	Notes
		min	max	min	max	min	max		
Read Cycle Time	$t_{RC}$	45	—	55	—	70	—	ns	1
Address Access Time	$t_{AA}$	—	45	—	55	—	70	ns	
Chip Select Access Time	$t_{ACS}$	—	45	—	55	—	70	ns	
Output Hold from Address Change	$t_{OH}$	5	—	5	—	5	—	ns	
Chip Selection to Output in Low Z	$t_{LZ}$	5	—	5	—	5	—	ns	2, 3, 7
Chip Deselection to Output in High Z	$t_{HZ}$	0	30	0	30	0	30	ns	2, 3, 7
Chip Selection to Power Up Time	$t_{PU}$	0	—	0	—	0	—	ns	7
Chip Deselection to Power Down Time	$t_{PD}$	—	40	—	40	—	40	ns	7

## ● Timing Waveform of Read Cycle No. 1<sup>(4)(5)</sup>



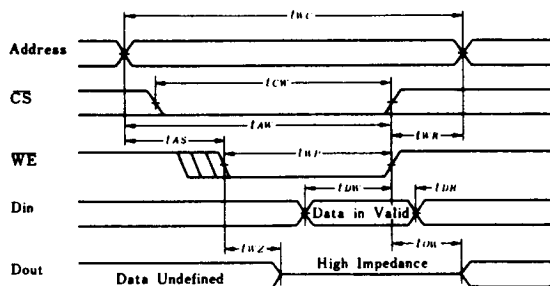
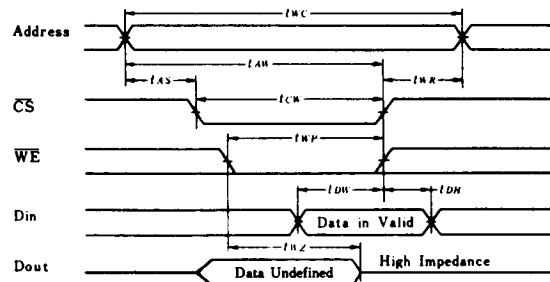
## ● Timing Waveform of Read Cycle No. 2<sup>(4)(6)</sup>



- Notes:
1. All Read Cycle timings are referenced from last valid address to the first transitioning address.
  2. At any given temperature and voltage condition,  $t_{HZ}$  max. is less than  $t_{LZ}$  min. both for a given device and from device to device.
  3. Transition is measured  $\pm 500$  mV from steady state voltage with specified loading in Load B.
  4.  $\overline{WE}$  is high for READ Cycle.
  5. Device is continuously selected, while  $\overline{CS} = V_{IL}$ .
  6. Address valid prior to or coincident with  $\overline{CS}$  transition low.
  7. This parameter is sampled and not 100% tested.

## ● WRITE CYCLE

Item	Symbol	HM6287-45		HM6287-55		HM6287-70		Unit	Notes
		min	max	min	max	min	max		
Write Cycle Time	$t_{WC}$	45	—	55	—	70	—	ns	2
Chip Selection to End of Write	$t_{CW}$	40	—	50	—	55	—	ns	
Address Valid to End of Write	$t_{AW}$	40	—	50	—	55	—	ns	
Address Setup Time	$t_{AS}$	0	—	0	—	0	—	ns	
Write Pulse Width	$t_{WP}$	25	—	35	—	40	—	ns	
Write Recovery Time	$t_{WR}$	0	—	0	—	0	—	ns	
Data Valid to End of Write	$t_{DW}$	25	—	25	—	30	—	ns	
Data Hold Time	$t_{DH}$	0	—	0	—	0	—	ns	
Write Enabled to Output in High Z	$t_{WZ}$	0	25	0	25	0	30	ns	3, 4
Output Active from End of Write	$t_{OW}$	0	—	0	—	0	—	ns	3, 4

● Timing Waveform of Write Cycle No. 1 ( $\overline{WE}$  Controlled)● Timing Waveform of Write Cycle No. 1 ( $\overline{CS}$  Controlled)

- Notes)
1. If  $\overline{CS}$  goes high Simultaneously with  $\overline{WE}$  high, the output remains in a high impedance state.
  2. All Write Cycle timings are referenced from the last valid address to the first transitioning address.
  3. Transition is measured  $\pm 500\text{mV}$  from steady state voltage with specified loading in Load B.
  4. This parameter is sampled and not 100% tested.

# ■ LOW $V_{CC}$ DATA RETENTION CHARACTERISTICS ( $T_a = 0$ to $+70^\circ\text{C}$ )

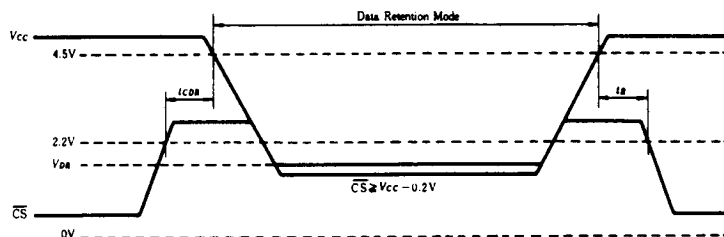
This characteristics is guaranteed only for L-version.

Parameter	Symbol	Test Condition	min.	typ.	max.	Unit
$V_{CC}$ for Data Retention	$V_{DR}$	$CS \geq V_{CC} - 0.2\text{V}$ $V_{in} \leq V_{CC} - 0.2\text{V}$ or $0\text{V} \leq V_{in} \leq 0.2\text{V}$	2.0	—	—	V
Data Retention Current	$I_{CCDR}$		—	1	$50^{*2}$	$\mu\text{A}$
Chip Deselect to Data Retention Time	$t_{CDR}$	See retention waveform	0	—	—	ns
Operation Recovery Time	$t_R$		$t_{RC}^{*1}$	—	—	ns

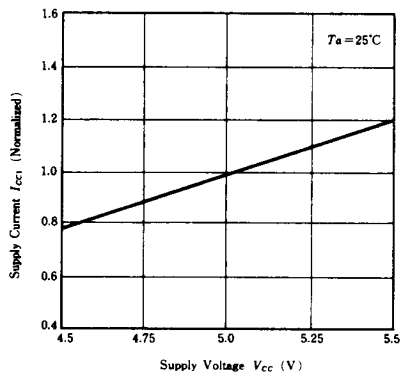
Note) \*1.  $t_{RC}$  = Read Cycle Time

\*2.  $V_{CC} = 3.0\text{V}$

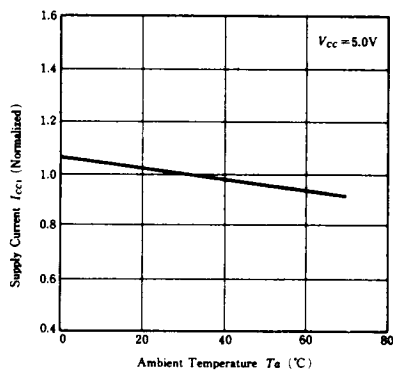
## ● LOW $V_{CC}$ DATA RETENTION WAVEFORM



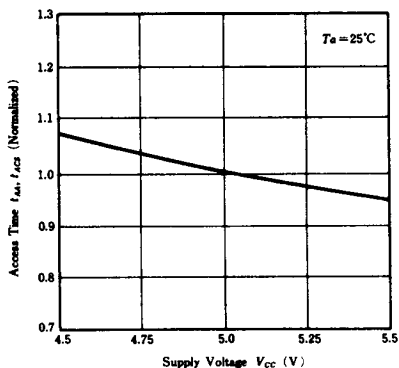
SUPPLY CURRENT vs. SUPPLY VOLTAGE



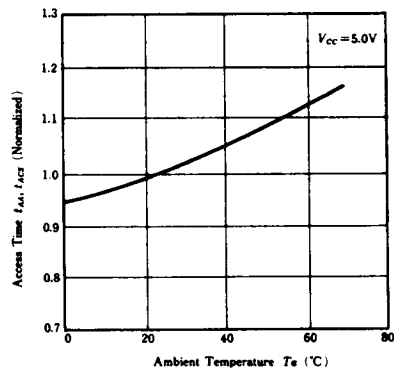
SUPPLY CURRENT vs. AMBIENT TEMPERATURE



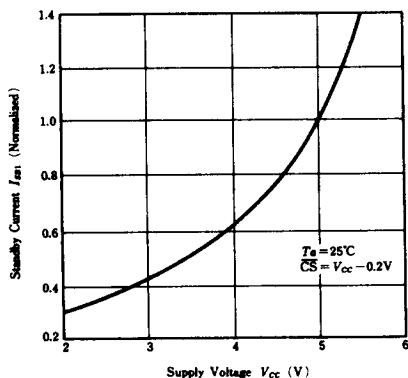
ACCESS TIME vs. SUPPLY VOLTAGE



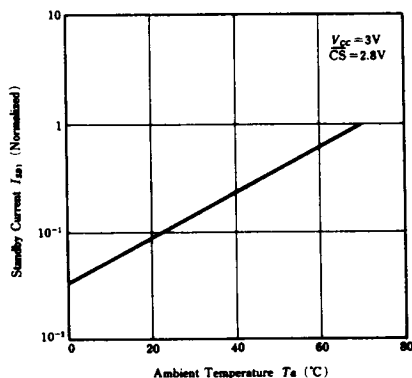
ACCESS TIME vs. AMBIENT TEMPERATURE



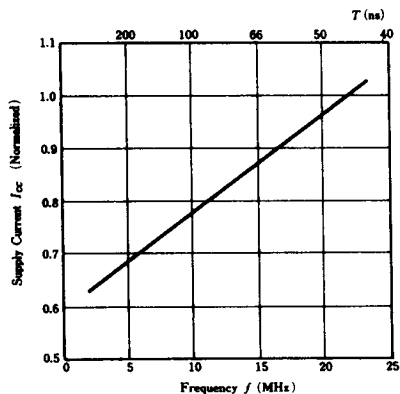
STANDBY CURRENT vs. SUPPLY VOLTAGE



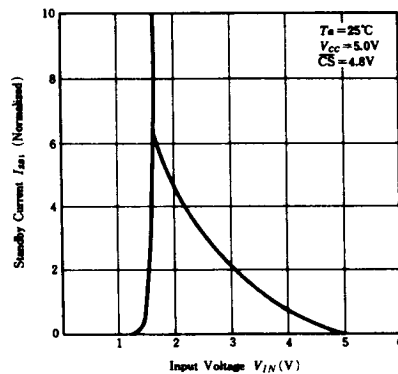
STANDBY CURRENT vs. AMBIENT TEMPERATURE



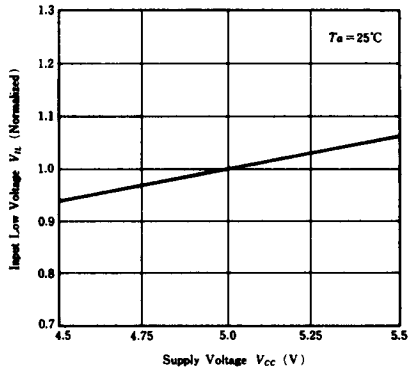
SUPPLY CURRENT vs. FREQUENCY



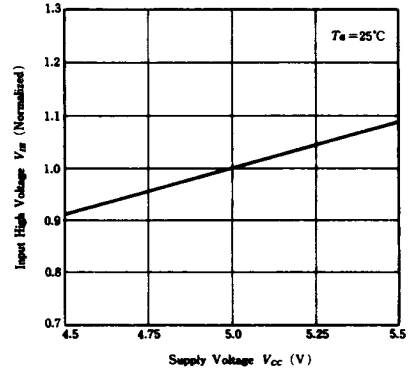
STANDBY CURRENT vs. INPUT VOLTAGE



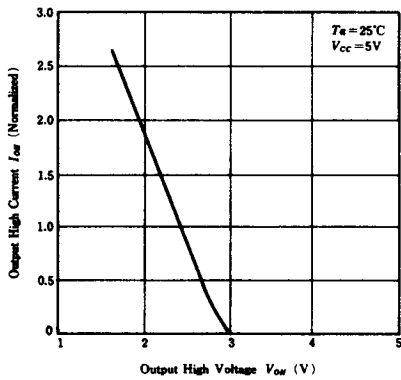
**INPUT LOW VOLTAGE vs.  
SUPPLY VOLTAGE**



**INPUT HIGH VOLTAGE vs.  
SUPPLY VOLTAGE**



**OUTPUT HIGH CURRENT vs.  
OUTPUT HIGH VOLTAGE**



**OUTPUT LOW CURRENT vs.  
OUTPUT LOW VOLTAGE**

